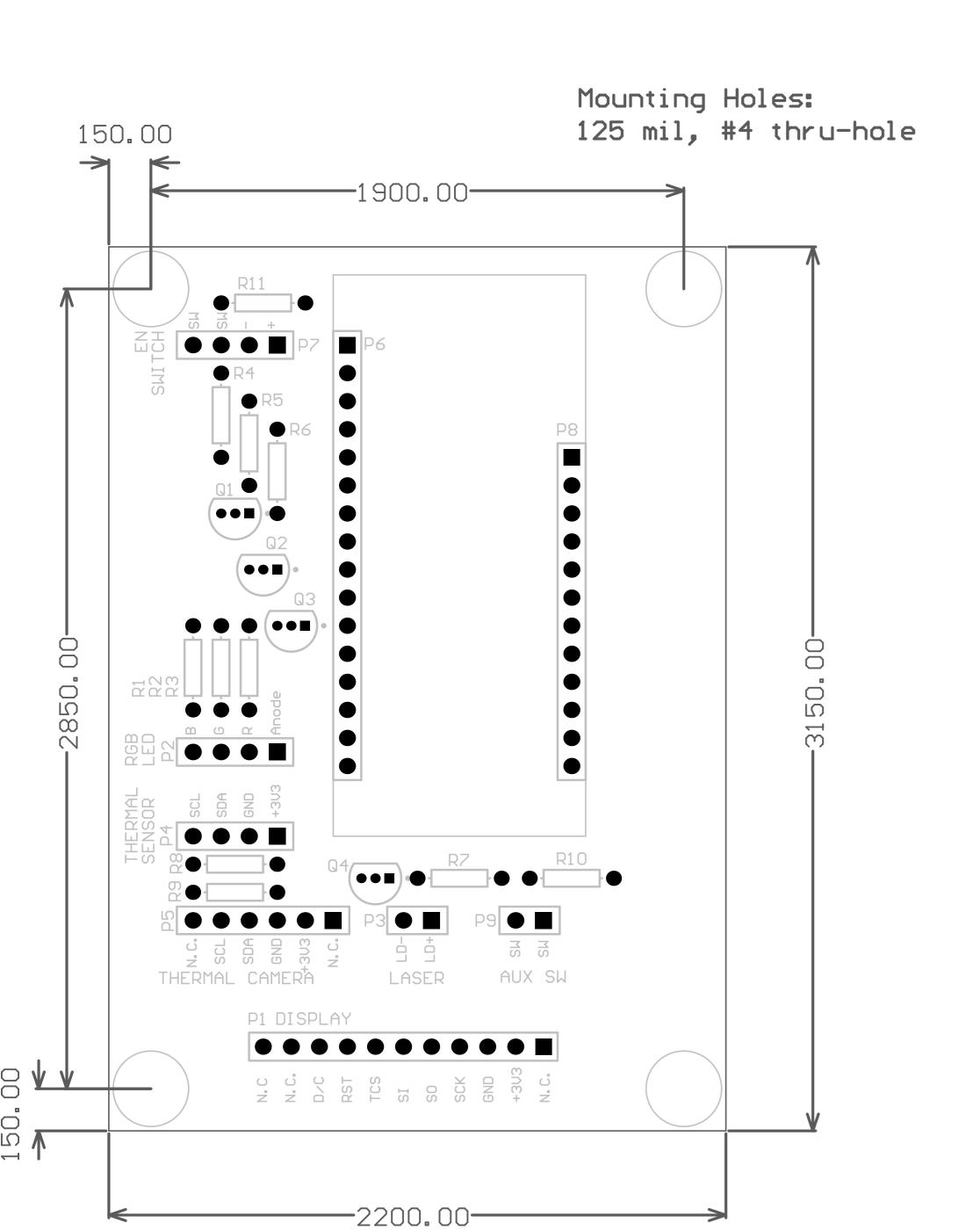


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	Copper	1.40mil		
	Dielectric 2	PP-006	10.00mil	4.1	
2	Internal Layer 1	Copper	1.38mil		
	Dielectric 1	FR-4	40.00mil	4.8	
3	Internal Layer 2	Copper	1.38mil		
	Dielectric 3	PP-006	10.00mil	4.1	
4	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Total board thickness:

66.36mil

- Notes
 1.) 4-layer FR4 stackup
 2.) finished board thickness 0.062" +/- 10%
 3.) N/A
 4.) soldermask: LPI green
 5.) silkscreen: white non-conductive epoxy ink

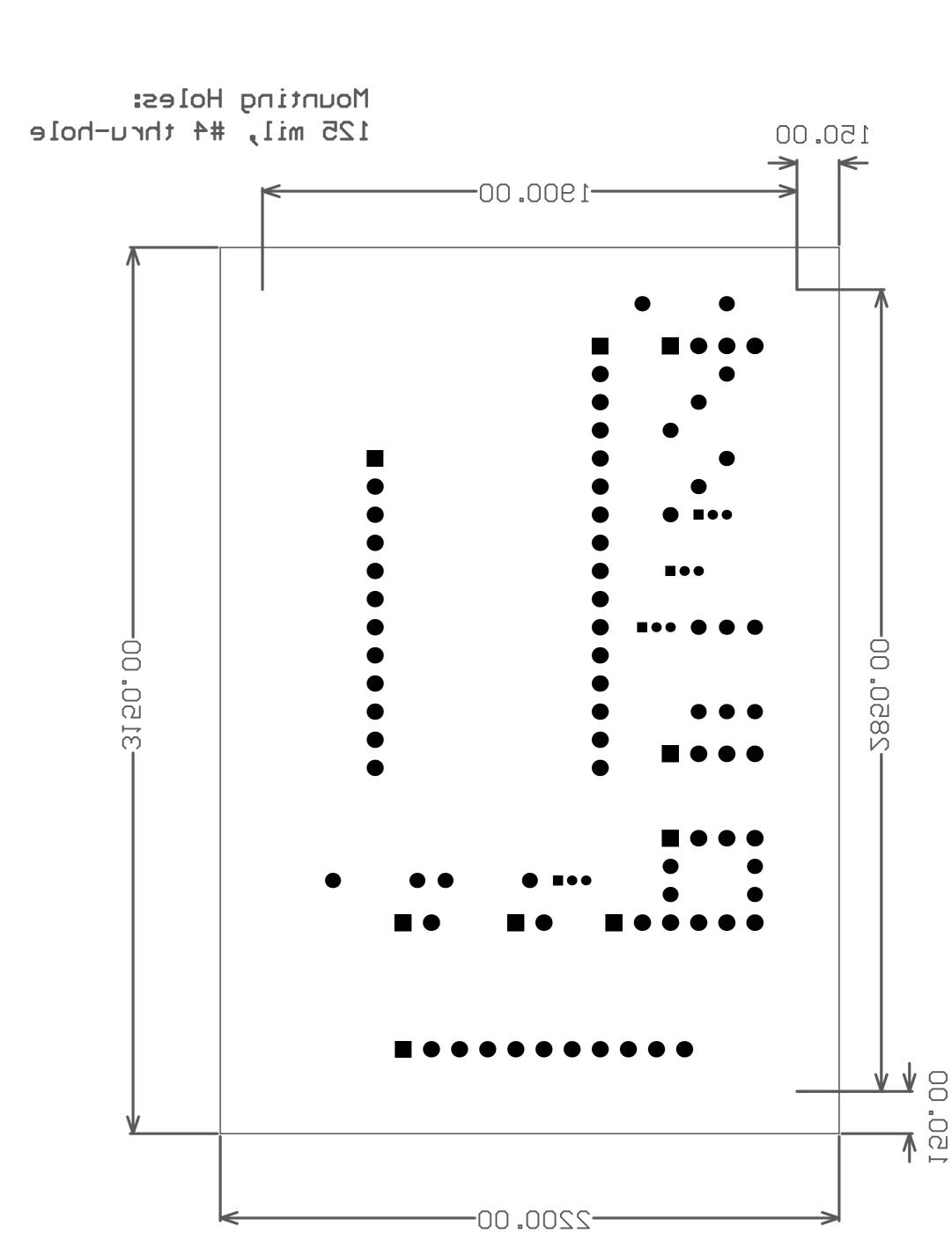


BOARD OUTLINE

TOP SILKSCREEN

Board Layer Stack	Constant	Thickness	Material	Name	Layer
				Top Overlay	
	3.5	0.40mil	Solder Resist	Top Solder	
		1.40mil	Copper	Top Layer	1
	4.1	10.00mil	PP-006	Dielectric 2	
		1.38mil	Copper	Internal Layer 1	2
	4.8	40.00mil	FR-4	Dielectric 1	
		1.38mil	Copper	Internal Layer 2	3
	4.1	10.00mil	PP-006	Dielectric 3	
		1.40mil	Copper	Bottom Layer	4
	3.5	0.40mil	Solder Resist	Bottom Solder	
				Bottom Overlay	

66.36mil Total board thickness:



Notes
1.) 4-layer FR4 stackup
2.) finished board thickness 0.062" +/- 10%
3.) N/A
4.) soldermask: LPI green
5.) silkscreen: white non-conductive epoxy ink

BOARD OUTLINE

BOTTOM SILKSCREEN